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**AMENDMENTS TO THE SPECIFICATION:**

Please CANCEL the first four full paragraphs on page 4 of the originally filed Specification.

Please CANCEL the paragraphs starting with, and including, the fourth full paragraph on page 7 of the originally filed Specification and ending with, and including, the second paragraph on page 10 of the originally filed Specification.

Please REPLACE the third full paragraph on page 18 of the originally filed Specification with the following amended paragraph:

The reinforcing components 56 and 57 are provided along the edge electrodes 53 and 54 with the microstrip line 55 described above, however a reinforcing layer 63 is provided with the microstrip line 60 of the fourth preferred embodiment shown in Fig. 6. This reinforcing layer 63 is defined by an insulating film with a small dielectric loss tangent, provided as a layer over the entire front 44 of the dielectric substrate 41 except for the portion where the strip conductor 51 is provided, and supports the edge electrodes 53 and 54 from the outside, similar to the reinforcing components 56 and 57 shown in Fig. 4. A ground electrode 43 is provided on the back of dielectric substrate 41.

Please REPLACE the paragraph bridging pages 19 and 20 of the originally filed Specification with the following amended paragraph:

The method for producing the microstrip line 65 will be briefly described with reference to Fig. 9. A ground electrode 43 is provided on the back of dielectric substrate 41. The pair of reinforcing components 66 and 67, having the inclined

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surfaces 68 and 69, is arranged substantially parallel at the location where the strip conductor 71 is to be formed on the front 44 of the dielectric substrate 41. The reinforcing components 66 and 67 are placed a specific distance apart and with the inclined surfaces 68 and 69 facing each other. The projected height  $h_1$  of the edge electrodes 73 and 74 is determined by the thickness of the reinforcing components 66 and 67.

Please REPLACE the second full paragraph on page 23 of the originally filed Specification with the following amended paragraph:

A microstrip line 100 includes a strip conductor 104 provided on a laminated substrate 101 including a first lamination component 102 and a second lamination component 103. The first lamination component 102 defines the dielectric substrate, and is made, for example, by laminating a plurality of dielectric sheets (green sheets) such that the thickness after baking will be about 60  $\mu\text{m}$ . These dielectric sheets are formed, for example, from a ceramic material with a high dielectric constant (such as a dielectric constant of about 30). More specifically, the first lamination component 102 is produced by laminating five dielectric sheets such that the substrate thickness after baking is about 300  $\mu\text{m}$ . The ground electrode 43 is provided on the back of the first lamination component 102. The bottom 107 of the line electrode 105 is provided in contact with the first lamination component 102, and the side surfaces 108 and 109 are provided in contact with the second lamination component 103.

Please REPLACE the third full paragraph on page 30 of the originally filed Specification with the following amended paragraph:

As shown in Fig. 20, three line formation holes 161, 162, and 163 are provided in a lateral row, equidistantly spaced and substantially parallel to the drawing direction, on

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the second lamination component 103 of the laminated substrate 101. Strip conductors 164, 165, and 166 are formed by filling in these line formation holes 161, 162, and 163, respectively, with a conductive paste. Laminated substrate 101 is provided including a first lamination component 102 and a second lamination component 103. Coupling electrodes 167 and 168 are provided on the front of the second lamination component 103 of the laminated substrate 101.